

Technical Data Sheet

EtroX[®] I CM UHT natural - ASTM

Typical characteristics

- Excellent thermo-oxidative stability (use up to 300°C)
- high dimensional stability under heat
- Extremely high heat resistance
- Very low creep tendency
- Nearly no moisture absorption

Typical industries

- Semiconductor Industry
- Elektronika
- Semiconductor Back-End applications
- Semiconductor Wafer Handling
- Semiconductor High and low temperature

| | Test method | Unit | Guideline value |
|--|--------------------------------|---------------------|-------------------|
| General properties | | | |
| Density | DIN EN ISO 1183-1 | g / cm ³ | 1.43 |
| Water absorption | DIN EN ISO 62 (23°C / 24h) | % | 0.06 |
| Water absorption | DIN EN ISO 62 (23°C / 48h) | % | 0.1 |
| Water absorption | DIN EN ISO 62 (23°C / 3 Weeks) | % | 0.4 |
| Mechanical properties | | | |
| Elongation at break | DIN EN ISO 527 | % | 4 |
| Tensile modulus of elasticity | DIN EN ISO 527 | MPa | 4800 |
| Tensile strength | DIN EN ISO 527 | MPa | 142 |
| Impact strength | DIN EN ISO 179 | kJ / m ² | 40 |
| Notched impact strength | DIN EN ISO 179 | kJ / m ² | 3 |
| Shore hardness | DIN EN ISO 868 | scale D | 90 |
| Elastic modulus of compression | DIN EN ISO 604 | MPa | 4000 |
| Thermal properties | | | |
| Glass transition temperature | ISO 11357-3 | °C | 270 |
| Temp. of deflection under load, 1.80 MPa | ISO 75-1/-2 | °C | 265 |
| Temp. of deflection under load, 0.45 MPa | ISO 75-1/-2 | °C | 304 |
| Electrical properties | | | |
| Volume resistivity | DIN EN 62631-3-1 | Ω * cm | >10 ¹¹ |



| | Test method | Unit | Guideline value |
|-----------------------------|----------------------|------|-----------------|
| Dielectric constant (1 MHz) | DIN EN IEC 62631-2-1 | | 3.3 |

